

Title (en)
SEGMENTED WAFER POLISHING PAD

Title (de)
SEGMENTIERTES POLIERKISSEN ZUM POLIEREN VON HALBLEITERSCHEIBEN

Title (fr)
ELEMENT DE POLISSAGE DE TRANCHE SEGMENTEE

Publication
EP 1328377 A1 20030723 (EN)

Application
EP 01976480 A 20011019

Priority
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• GB 0025745 A 20001020

Abstract (en)
[origin: WO0232624A1] Working plate (10) is formed of forty-eight sections (10'), with groove (12) extending through the majority of the thickness of the plate. In one form, dovetail grooves are machined to the back of the sections of the plates (10') attached to the base plate (19). In an alternative arrangement, fixing rails are attached to the backs of the sections and the dovetail grooves are in the base plate (19).

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IPC 8 full level
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CPC (source: EP US)
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Citation (search report)
See references of WO 0232624A1

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